Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Ti, V/Ni, Au**

**Bond Pad Size: .004” min**

**Backside Potential: DRAIN**

**Mask Ref: IX7X**

**APPROVED BY: DK DIE SIZE .283” X .348” DATE: 7/21/21**

**MFG: IXYS THICKNESS .013” P/N: IXFD24N50**

**DG 10.1.2**

#### Rev B, 7/19/02